

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: Masaru SHIRAI et al. Group Art Unit: 1725  
Serial No.: 10/598,142 Examiner: D'ANIELLO, N.  
Filed : August 18, 2006 Confirmation No.:1550  
  
For: **HEATER, REFLOW APPARATUS, AND SOLDER BUMP FORMING METHOD AND APPARATUS**

**REQUEST FOR EXTENSION OF TIME**

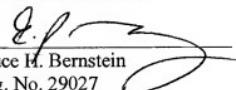
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Sir:

Please extend the time for response to the Official Action dated March 14, 2011 by one month from June 14, 2011 to July 14, 2011. The amount of \$130.00 is submitted concurrently herewith as payment for the fee.

The U.S. Patent and Trademark Office is hereby authorized to credit any overpayment or charge any additional fee to Deposit Account No.19-0089.

Respectfully submitted,  
Masaru SHIRAI et al.

  
Bruce M. Bernstein  
Reg. No. 29027

July 14, 2011  
GREENBLUM & BERNSTEIN, P.L.C.  
1950 Roland Clarke Place  
Reston, VA 20191  
(703) 716-1191

Enoch E. Peavey  
Reg. No. 57,686